

Substrate: 3.18mm \pm 0.25mm [0.125" \pm 0.001"] FR4/G10 or equivalent high temp material. 17 μ m [1/2 oz.] Cu clad. SnPb plating.




Solder ball: Eutectic Sn63Pb37

Description: BGA Surface Mount Adaptor

169 position surface mount land pattern to solder balls. To be used with GHz sockets.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA169F-B-05 Drawing		Status: Released	Scale: 3:1	Rev: B
	© 2002 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com		Drawing: H. Hansen	
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